



Final Product/Process Change Notification

Document #:FPCN26707X

Issue Date:08 Jul 2026

Title of Change:	Additional Assembly and Test site for WDFN8 package at onsemi Leshan, China	
Proposed First Ship date:	15 Oct 2026 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Assembly site marking	
Change Category:	Assembly Change, Test Change	
Change Sub-Category(s):	Manufacturing Site Addition	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Leshan, China	None	
Description and Purpose:		
onsemi wishes to inform customers that we are expanding Assembly and Test operations for the WDFN8 package to our onsemi Leshan, China facility.		
The detail change summary as per table below.		
	Before	After
Assembly & Test Site	onsemi Tarlac, Philippines Hana Semiconductor, Thailand UTAC, Thailand UTL3, Thailand	onsemi Tarlac, Philippines Hana Semiconductor, Thailand UTAC, Thailand UTL3, Thailand onsemi Leshan, China
	Existing sites	Additional site: onsemi Leshan, China
Die Attach	ABLETHERM 8600	CRM1800B
Bond Wire	2mils Au / Pd coated / Cu wire	2mils Cu wire
Mold Compound	CEL9220HF13H, G770 HM type D, G700LTD	G770 HM type D



Final Product/Process Change Notification

Document #:FPCN26707X

Issue Date:08 Jul 2026

Marking(WDFN8 ,HANA,UTL3,UTAC)	Z/A = Assembly Plant Code XY/2= 2digit date code K/KK=lot run code XXXX=device code	&Z&XY&KK XXXX XXXX XXXX &Z&2&K XXXX XXXX &Z&2&K XXXX XXXX &A&KK&XY	A: Assembly Plant Code L: wafer lot number YW: Year Workweek XXXX=device code	XXXXXX XXXXXX ALYW
---------------------------------------	--	---	--	---

There is no change of form, fit, and function.

Reliability Data Summary:

QV DEVICE NAME: FDMC7680

RMS: S107158

PACKAGE: WDFN8

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST for surface mount pkgs only	-	0/924
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Solderability	JSTD002	Ta = 245°C, 5 sec	-	0/45
Physical Dimensions	JESD22-B120		-	0/30

QV DEVICE NAME: FDMC2610

RMS: S107721

PACKAGE: WDFN8

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST for surface mount pkgs only	-	0/924
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Solderability	JSTD002	Ta = 245°C, 5 sec	-	0/45
Physical Dimensions	JESD22-B120		-	0/30



Final Product/Process Change Notification

Document #:FPCN26707X

Issue Date:08 Jul 2026

Electrical Characteristics Summary:

The electrical characteristics are not impacted

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**

Current Part Number	New Part Number	Qualification Vehicle
FDMC86102LZ-P	#NONE	FDMC2610
FDMC86320	#NONE	FDMC2610
NTTFS115P10M5	#NONE	FDMC7680
FDMC7680	#NONE	FDMC7680
FDMC86240	#NONE	FDMC2610
FDMC86102LZ	#NONE	FDMC2610
FDMC86261P	#NONE	FDMC2610
FDMC7672	#NONE	FDMC7680
FDMC86262P	#NONE	FDMC7680
FDMC86520L	#NONE	FDMC2610
FDMC86102L	#NONE	FDMC2610
FDMC86139P	#NONE	FDMC2610
FDMC2523P	#NONE	FDMC7680